

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped silicon	Silicon (Si)	7440-21-3	0.33392	100.0	4.8
Subtotal				0.33392	100	4.8
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.01037	100.0	0.1491
	Pure metal	Aluminium (Al)	7429-90-5	0.15861	100.0	2.28
Subtotal				0.16898	200	2.4291
Post-plating	Pure Metal	Tin (Sn)	7440-31-5	1.73916	100.0	25
Subtotal				1.73916	100	25
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.02337	0.04	0.336
	Copper alloy	Iron (Fe)	7439-89-6	0.05844	0.1	0.84
	Copper alloy	Copper (Cu)	7440-50-8	58.35382	99.86	838.824
Subtotal				58.43563	100	840
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	3.4044	8.7	48.9375
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	6.26096	16.0	90
	Filler	Silica fused	60676-86-0	29.34825	75.0	421.875
	Carbon Black	Carbon black	1333-86-4	0.11739	0.3	1.6875
Subtotal				39.131	100	562.5
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.00957	5.0	0.1375
	Lead alloy	Silver (Ag)	7440-22-4	0.00478	2.5	0.06875
	Lead alloy	Lead (Pb)	7439-92-1	0.17696	92.5	2.54375
Subtotal				0.19131	100	2.75
Total				100	100	1437.4791

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